

AN14515

FRDM-MCXW71 RF System Evaluation Report for Bluetooth Low Energy Applications with Interferer Coexistence

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Application note

Document information

Information	Content
Keywords	MCX W71, MCU, RF, Bluetooth, Bluetooth LE, FRDM-MCXW71, AN14515
Abstract	The document describes test setup and provides steps to perform the RF system evaluation test of FRDM-MCXW71 for Bluetooth LE applications (2FSK modulation) with coexistence of the following interferers: noise, Sinewave, Bluetooth audio, and Wi-Fi.



1 Introduction

The document describes test setup and provides steps to perform the RF system evaluation test of FRDM-MCXW71 for Bluetooth LE applications (2FSK modulation) with coexistence of the following interferers: noise, Sinewave, Bluetooth audio, and Wi-Fi.

To get the MCX W71 radio parameters, see the *MCX W71 Data Sheet* (document [MCX W71](#)).

For more information about the FRDM-MCXW71 board, see *Hardware Design Considerations for MCX W71 Bluetooth LE Devices* (document [UG10146](#)). Find the schematic and design files at this [link](#).

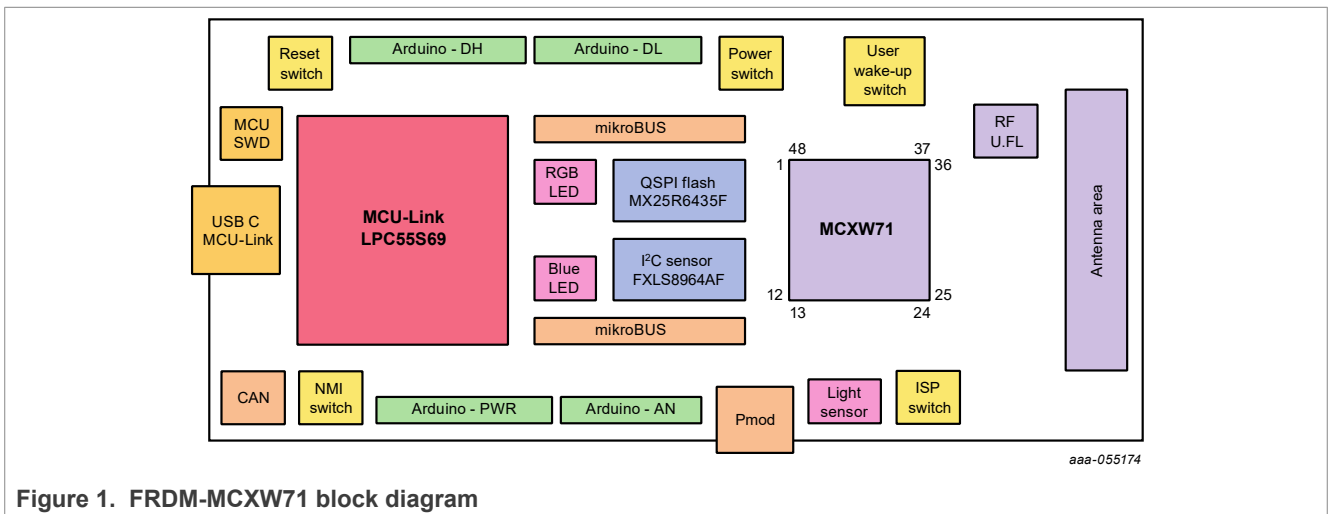
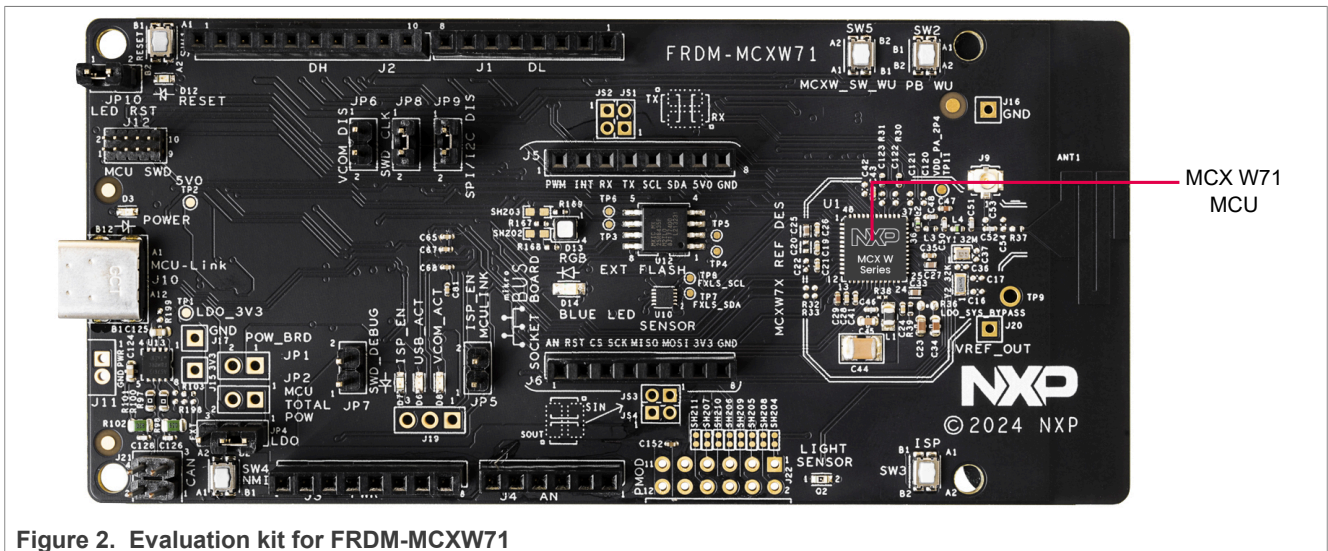


Figure 1. FRDM-MCXW71 block diagram

Figure 2 shows the top-view of the FRDM-MCXW71 board.



- C/N versus frequency
- C/N versus level
- CW interferer
- Adjacent-channel interference (ACIs)
- Co-channel
- Bluetooth LE interferer
- Bluetooth LE ACIs
- Bluetooth LE co-channel
- Wi-Fi interferer
- Wi-Fi ACIs
- Wi-Fi co-channel

1.2 Software

Before measuring, a binary code (connectivity software) must be loaded into the board's flash memory.

The MCX W71 page describes how to use the FRDM-MCXW71 board to [load the code](#). The binary code that is used for the evaluation tests are the Connectivity Software package GenFSK protocol (2FSK modulation) and the HCI_blackbox. The Teraterm terminal emulator is used to communicate with the MCX W71 MCU.

1.3 List of equipment

The equipments used to perform the TX and RX measurements are listed as follows:

- Spectrum analyzer
- Rohde & Schwarz (R&S) SFU - used as an interferer source for Bluetooth LE – it can be any generator with ARbitrary signal
- MXG (Agilent N5182A)
- Agilent SML03
- Agilent 33250A
- DC power supply
- PC equipped with an IEEE-488 (GPIB) card
- Noise interference

1.4 Test bench setup

[Figure 3](#) shows the noise interferer test setup.

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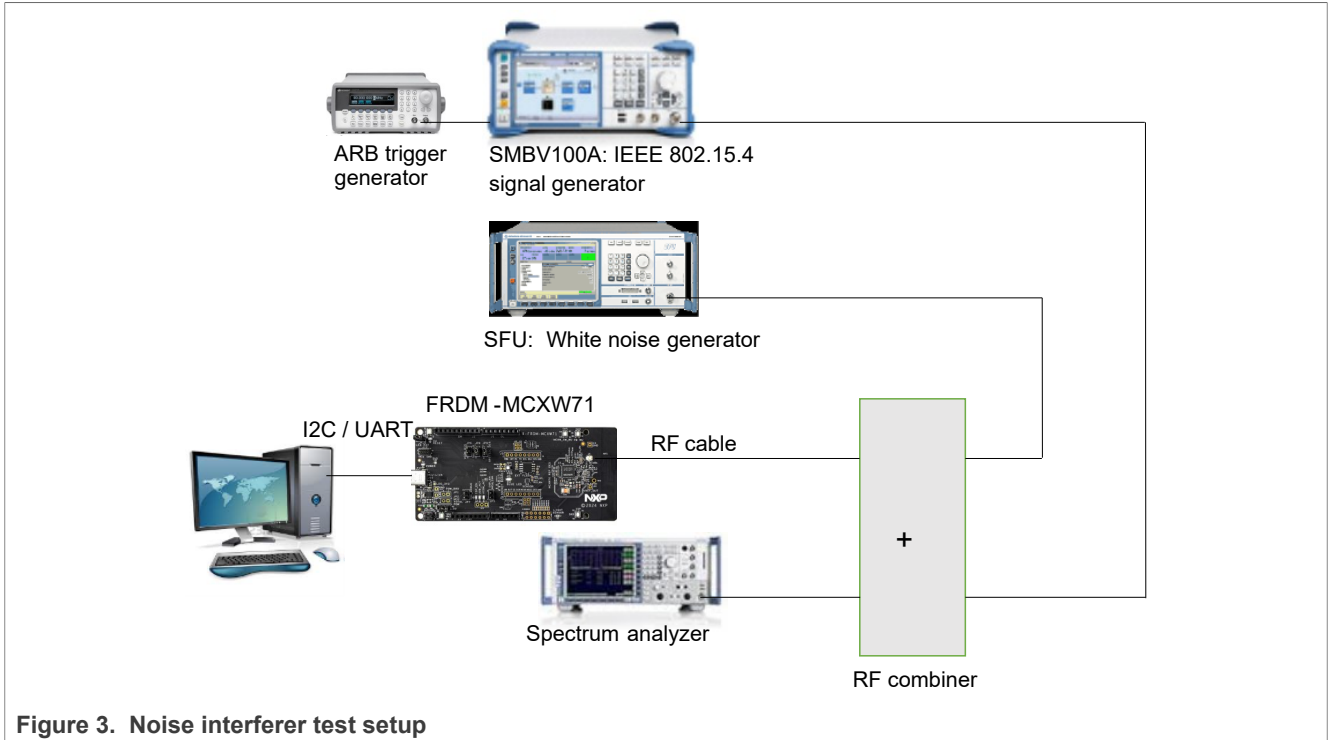


Figure 3. Noise interferer test setup

1.5 White noise interferer setup

Carrier-to-noise (C/N) measurement highlights the demodulator (base-band) section performance.

A white noise is added into the wanted channel. The noise power is increased until the criteria PER<30.8 % is reached. The C/N is calculated on 1.02 MHz bandwidth.

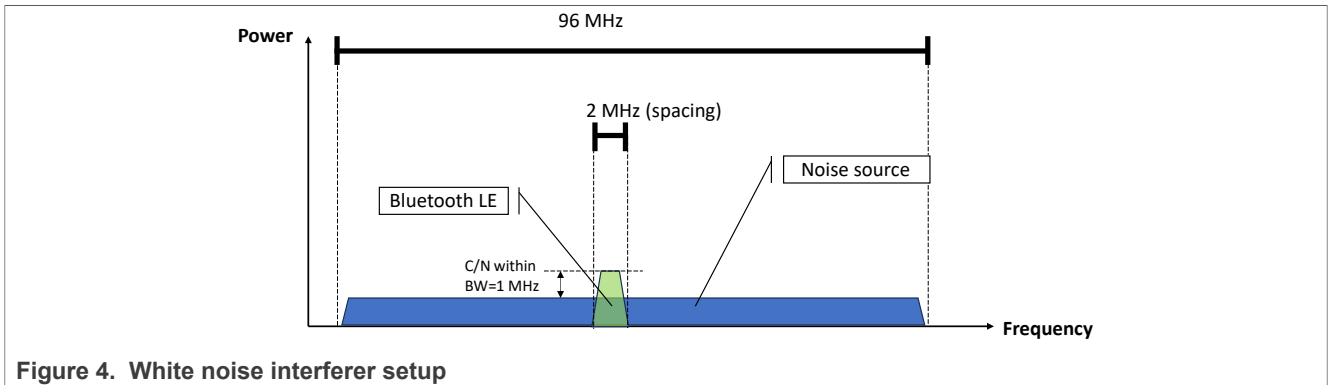


Figure 4. White noise interferer setup

1.6 C/N versus frequency

This section describes the test methods and results to carrier-to-noise ratio (C/N) from 2.402 GHz to 2.48 GHz.

1.6.1 Test method

- Set the MCX W71 radio to: RX mode, modulated, continuous mode, frequency: from channel 0 (2.402 MHz) to channel 39 (2.48 GHz).
- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: from channel 0 (2.402 MHz) to channel 39 (2.48 GHz), constant RF output level = -40 dBm.

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- Set the analyzer for power calibration, -40 dBm on Bluetooth LE signal and white noise (BW=96 MHz on SFU). Center frequency = 2.435 GHz, span = 10 MHz, BW=2 MHz.
- C/N is set to +10 dB and decreased by step of 0.1 dB until the criteria PER<30.8 % is reached for all channels.

1.6.2 Result

Figure 5 shows the test result for C/N versus frequency ranging from 2.402 GHz to 2.48 GHz.

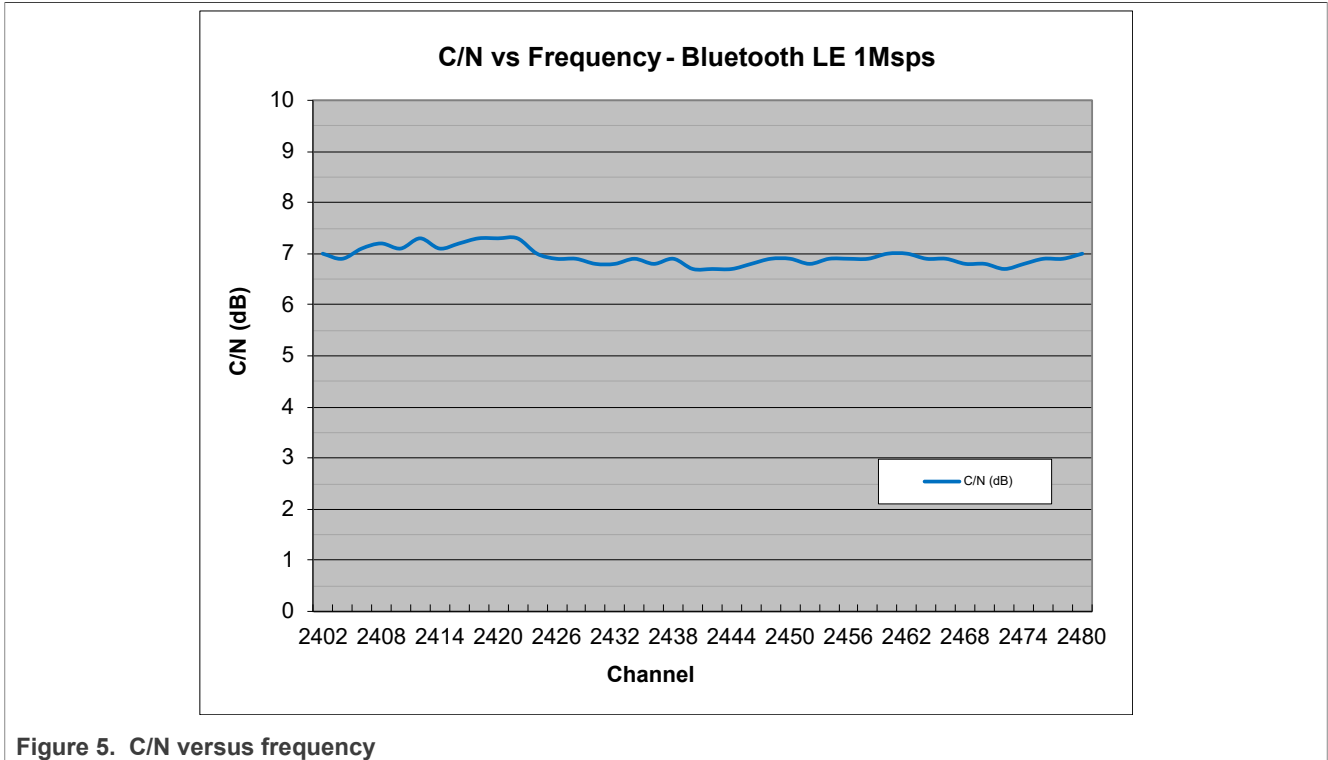


Figure 5. C/N versus frequency

1.6.3 Conclusion

C/N performance is independent from the channel (purely base-band performance).

C/N is 7 dB.

1.7 PER versus C/N

This section describes the test methods and results to packet error rate (PER) depending on the carrier-to-noise ratio (C/N).

1.7.1 Test method

- Set the MCX W71 radio to: RX mode, modulated, continuous mode, frequency: channel 19 (2.44 MHz).
- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: channel 19 (2.44 MHz), constant RF output level = -40 dBm.
- Set the analyzer for power calibration @2.44GHz, - 40 dBm on Bluetooth LE signal and White Noise (BW=96 MHz on SFU). Center frequency = 2.435 GHz, span = 10 MHz, BW = 2 MHz.
- PER is measured for various C/N values from 1 to 11 by a step of 0.5 dB.

1.7.2 Result

Figure 6 shows the test result for PER versus C/N.

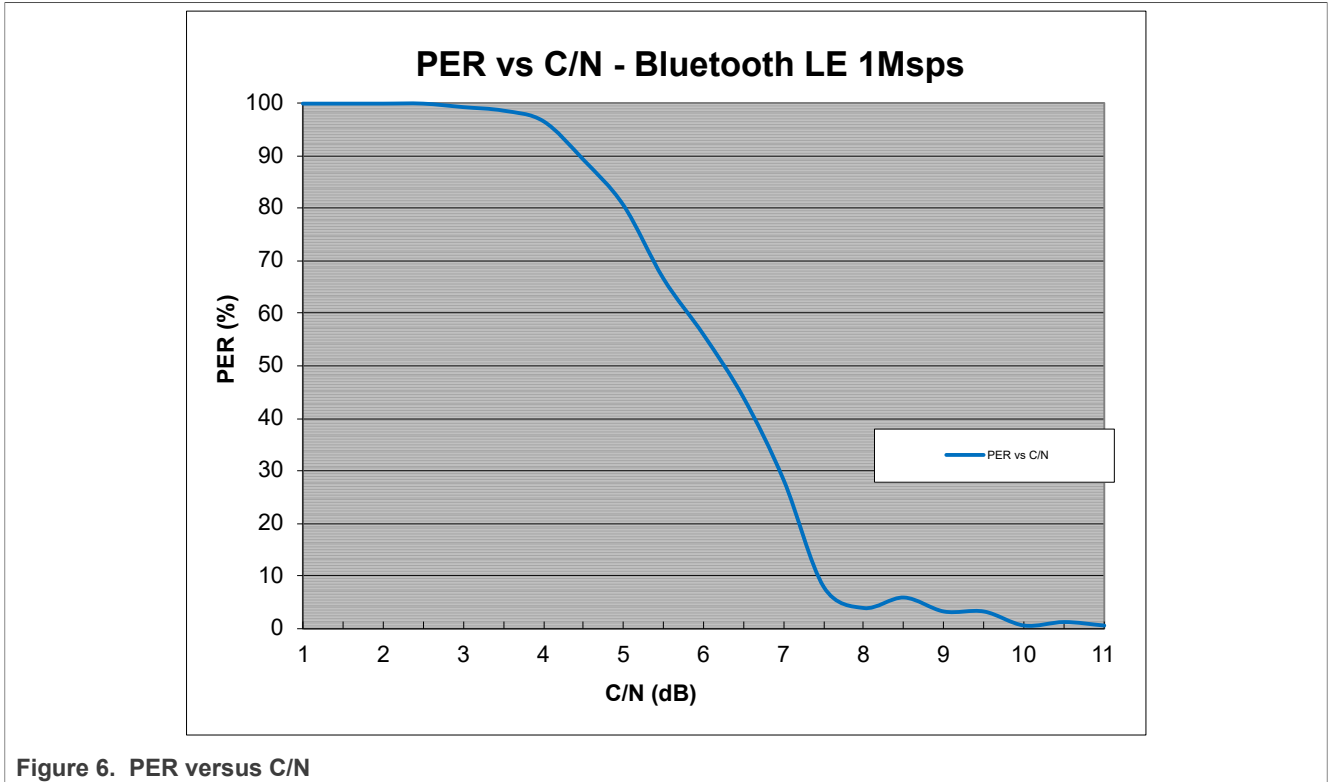


Figure 6. PER versus C/N

1.7.3 Conclusion

PER degrades smoothly when the noise increases. There is no abrupt degradation.

1.8 C/N versus level

This section describes the test methods and results to the carrier-to-noise ratio (C/N) versus Input level from -10 dBm to -101 dBm.

1.8.1 Test method

- Set the MCX W71 radio to: RX mode, modulated, continuous mode, frequency: channel 19 (2.44 MHz).
- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: from channel 19 (2.44 MHz), various RF output level from -20 dBm to the sensitivity level +1 dBm.
- Set the analyzer for power calibration on Bluetooth LE signal and white noise (BW=96 MHz on SFU). Center frequency = 2.435 GHz, span = 10 MHz, BW=2 MHz.
- A pure Sinewave is swept from channel 0 (2.402 GHz) to channel 39 (2.48 GHz) with a constant level set to -20 dBm.
- PER is measured for various constant RF input level and decreasing the C/N values until the PER criteria (<30.8 %) is reached.

1.8.2 Result

Figure 7 shows the test result for C/N versus Input level.

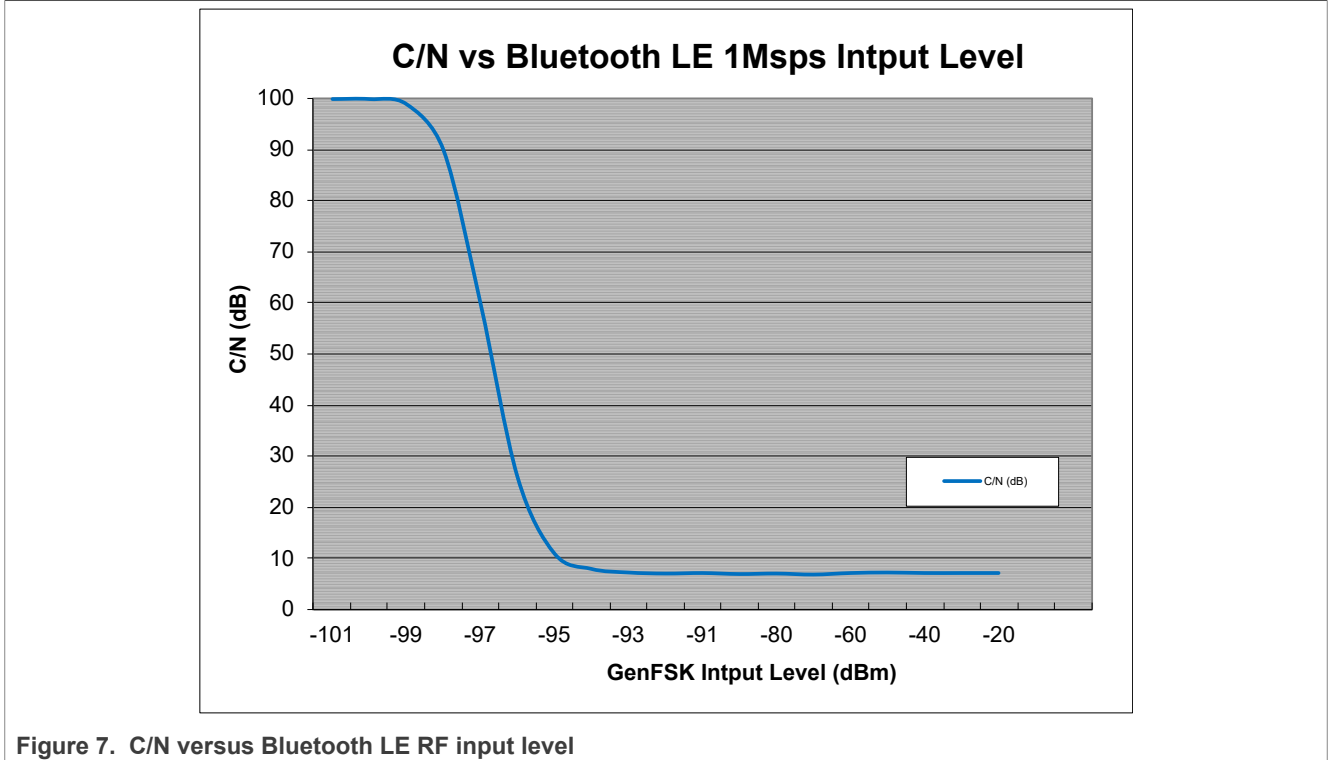


Figure 7. C/N versus Bluetooth LE RF input level

1.8.3 Conclusion

- For very low levels, both receiver noise (noise figure) and demodulator performance contribute to overall C/N performance.
- For higher level, the C/N is constant (independent from the receiver section).

2 Sinewave interference

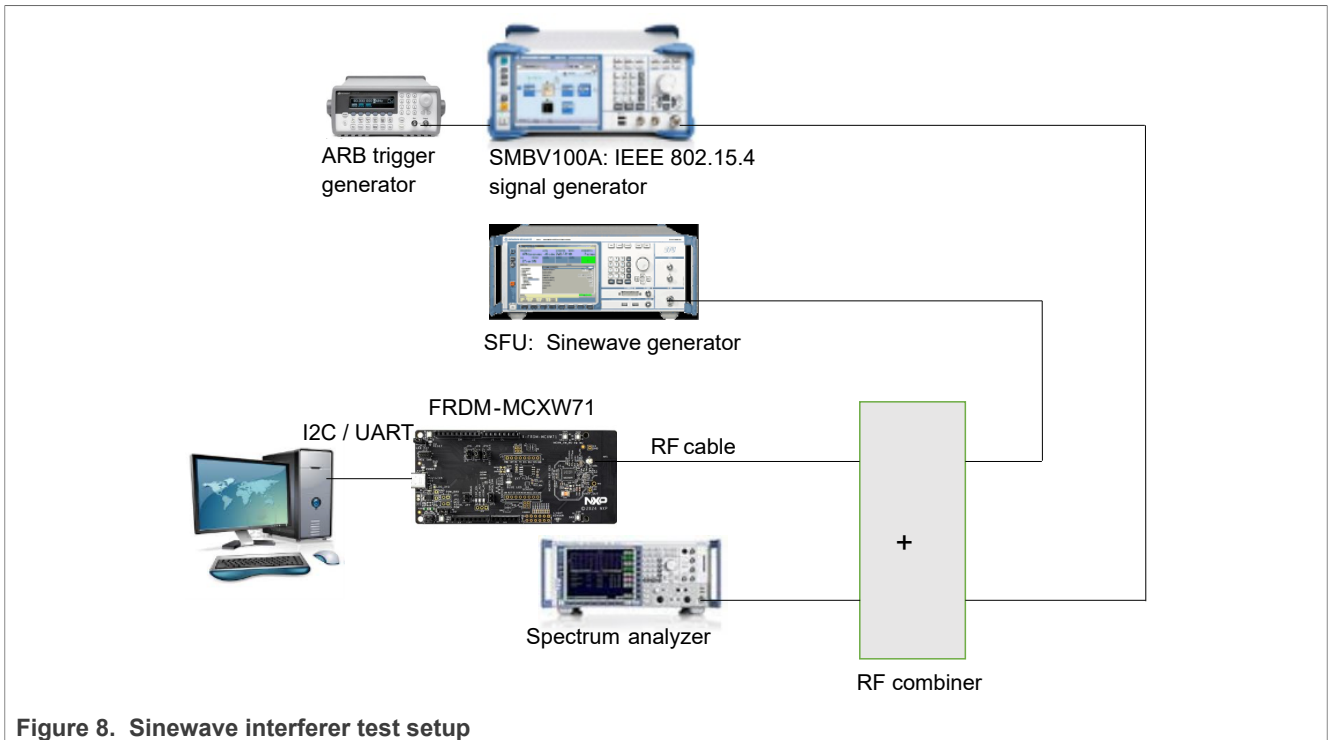
This section describes the test bench setup, test methods, and results to packet error rate (PER) depending on the Sinewave interferer.

2.1 Test setup

This section describes the Sinewave signal and Sinewave interferer test setup.

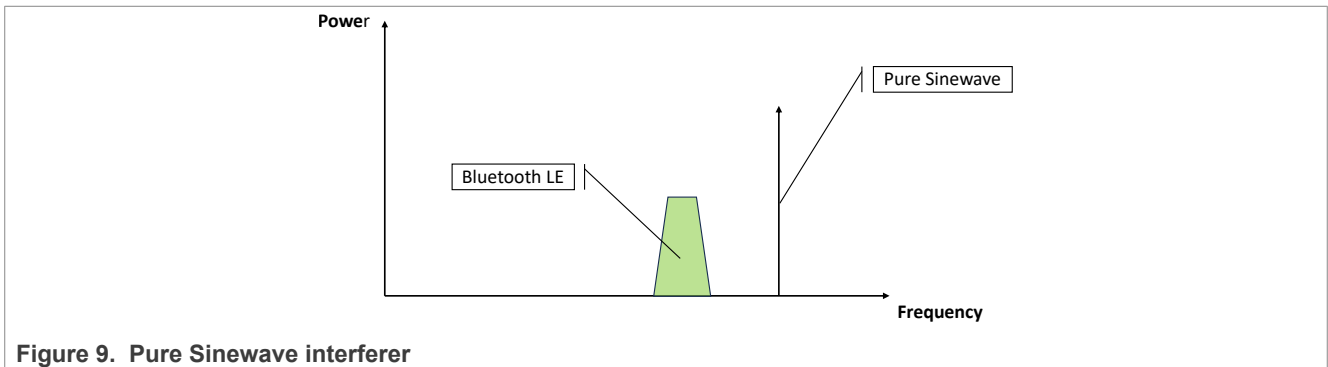
2.1.1 Test bench

Figure 8 shows the Sinewave interferer test setup.



2.1.2 Signal definition

A pure Sinewave is used in this test case to measure the ACIs (N+/-8) and co-channel immunity. The Sinewave power is increased until the criteria PER < 30.8 % is reached.



2.2 Sinewave interference test

This section describes the test methods and results to packet error rate (PER) depending on the Sinewave interferer.

2.2.1 Test method

- Set the MCX W71 radio to: RX mode (Bluetooth LE 1 Msps, 2 Msps, 500 kps or 125 kps), modulated, continuous mode, frequency: channel 19 (2.44 MHz).
- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: channel 19 (2.44 MHz).

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- Set the analyzer for power calibration on Bluetooth LE signal and Sinewave (-20 dBm).
- A pure sinewave is swept from channel 0 (2.402 GHz) to channel 39 (2.48 GHz) with a constant level set to -20 dBm.
- Bluetooth LE power is decreased until PER criteria (<30.8 %) is reached.

2.2.2 Result

Figure 10 shows the test result.

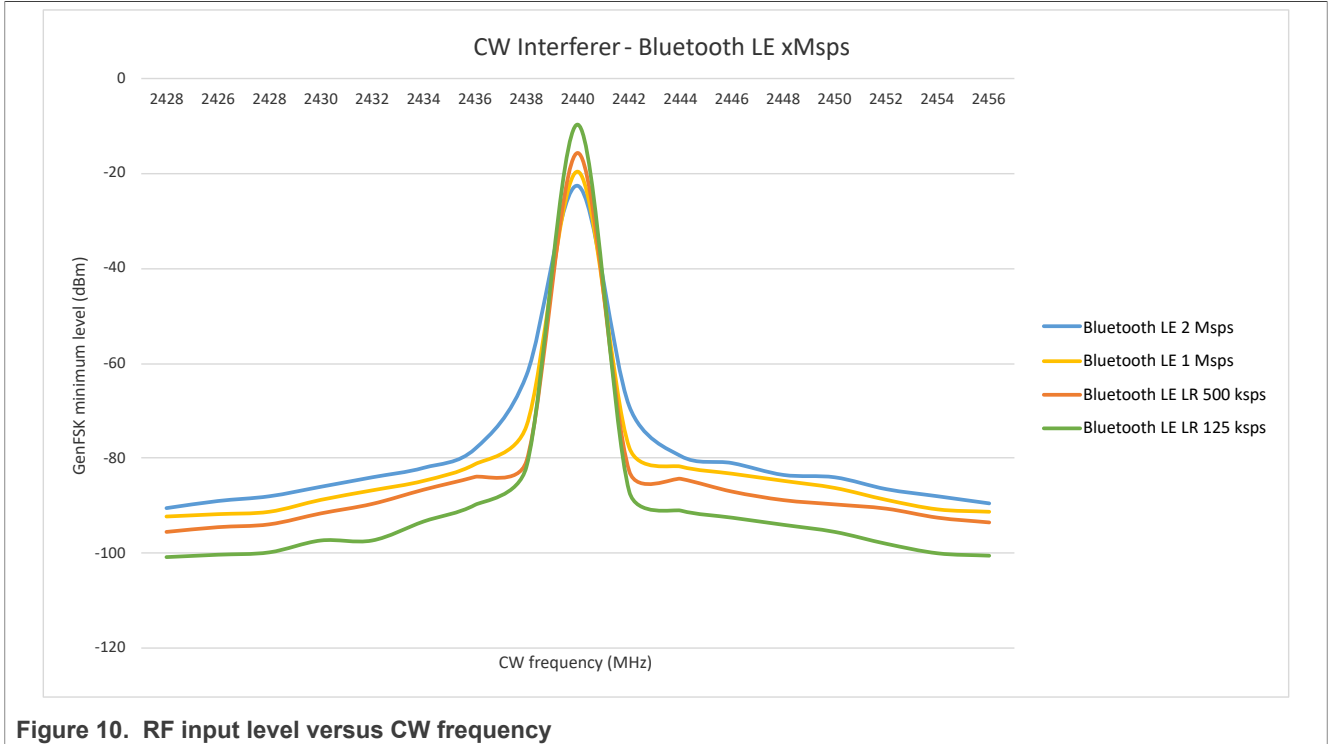


Figure 10. RF input level versus CW frequency

2.3 Conclusion

A Sinewave at a slight high level (-20 dBm) acts as a blocker. The receiver regulates its gain; therefore, the noise figure increases.

3 Bluetooth audio interference

This section describes the test bench setup, test methods, and results to PER depending on the Bluetooth audio interferer.

3.1 Test setup

This section describes the Bluetooth interferer signal and Bluetooth LE interferer test setup.

3.1.1 Test bench

Figure 11 shows the Bluetooth LE interferer test setup.

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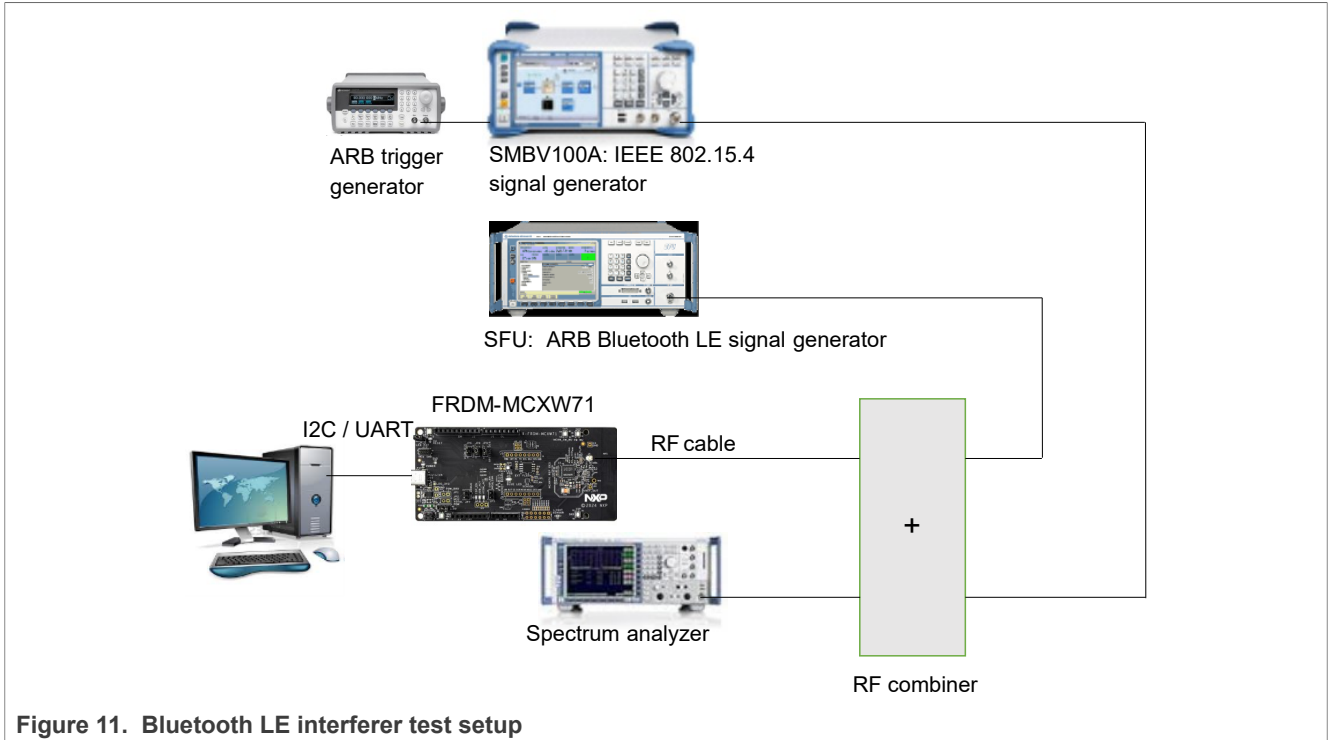


Figure 11. Bluetooth LE interferer test setup

3.1.2 Signal definition

The following measurements have been made by capturing 1 channel (case 1) from a smartphone Bluetooth Audio Stream.

The Bluetooth interferer is set to a constant level at -40 dBm. Its frequency is swept from -5 MHz to +5 MHz around Bluetooth LE channel. Duty cycle is forced to 5 %.

Bluetooth LE RR level is decreased until the criteria PER<30.8 % is reached.

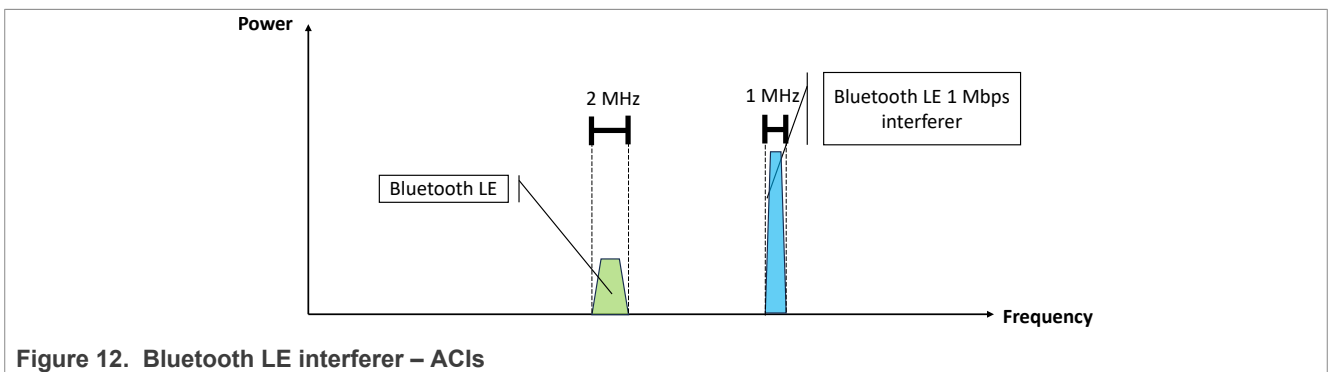


Figure 12. Bluetooth LE interferer – ACIs

3.2 Bluetooth audio interference test

This section describes the test methods and results to PER depending on the Bluetooth audio interferer.

3.2.1 Test method

- Set the MCX W71 radio to: RX mode, modulated, continuous mode, frequency: channel 19 (2.44 MHz).

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- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: channel 0 (2.402 GHz), 19 (2.44 MHz), and 39 (2.48 GHz).
- Set the analyzer for power calibration on Bluetooth LE signal and Bluetooth Audio signal.
- Bluetooth Audio stream is set to a level = -40 dBm and frequency from -5 MHz to +5 MHz by step of 1 MHz around the wanted channel frequency. Duty cycle is forced to 5 %.
- Bluetooth LE power is decreased until PER criteria (<30.8 %) is reached.

3.2.2 Result

Figure 13 shows the test result.

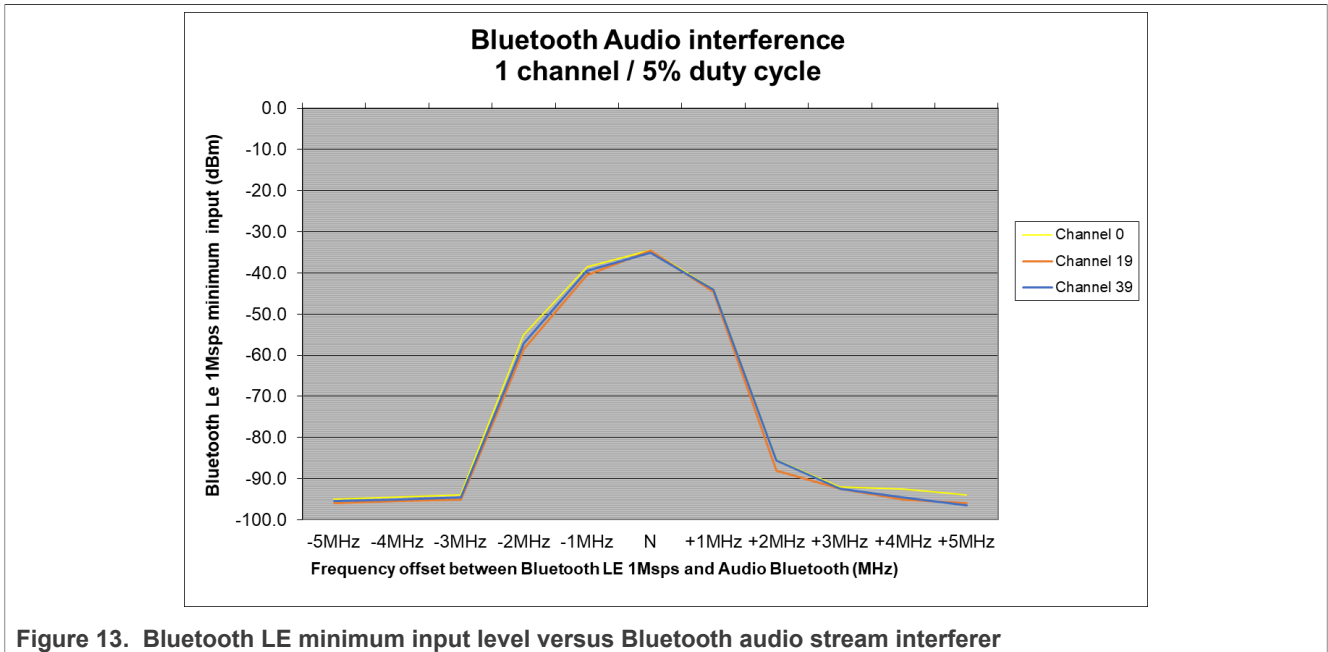


Figure 13. Bluetooth LE minimum input level versus Bluetooth audio stream interferer

3.2.3 Conclusion

- For co-channel, the carrier-to-interference ratio (C/I) is +4.5 dB (Bluetooth LE ch0, 19 or 39).
- For a Bluetooth channel outside the receiver bandwidth, the immunity performance increases rapidly.

4 Wi-Fi interference

This section describes the test bench setup, test methods, and results to packet error rate (PER) depending on the Wi-Fi interferer.

4.1 Test setup

This section describes the Wi-Fi interferer signal and Wi-Fi interferer test setup.

4.1.1 Test bench

Figure 14 shows the Wi-Fi interferer test setup.

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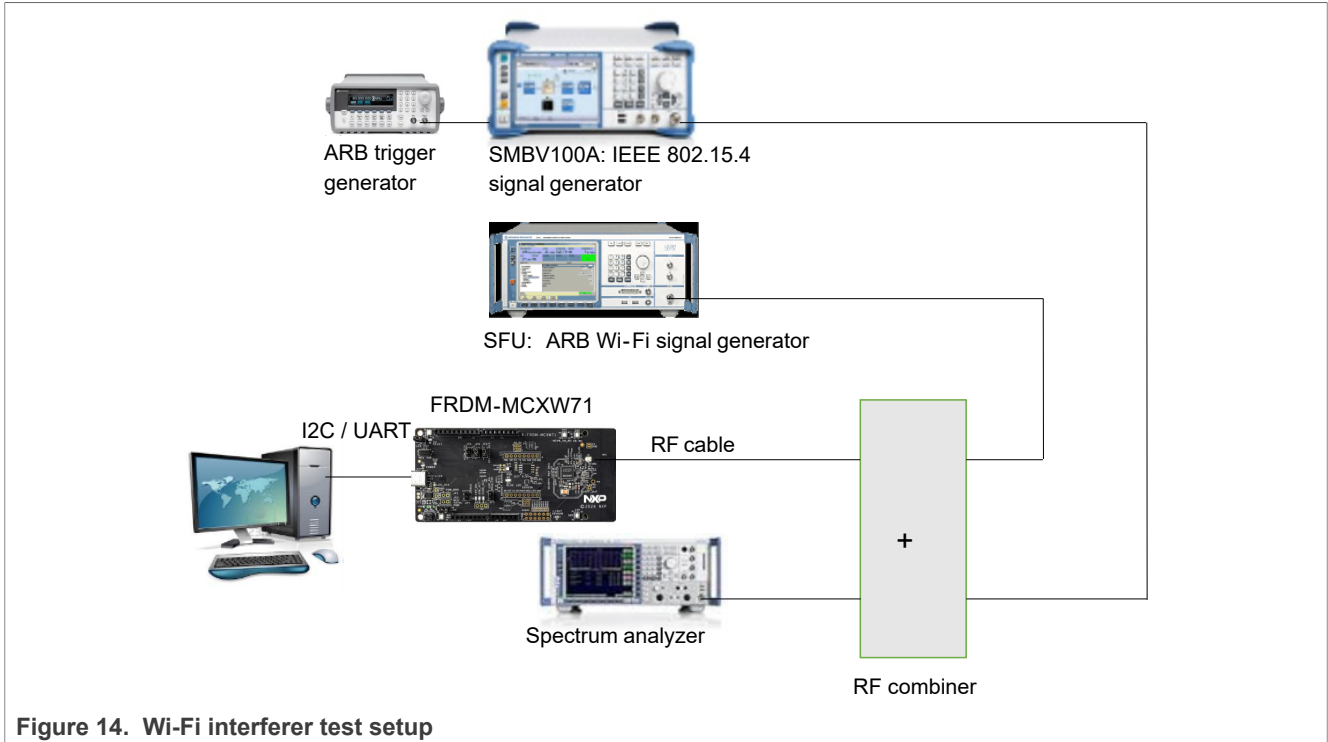


Figure 14. Wi-Fi interferer test setup

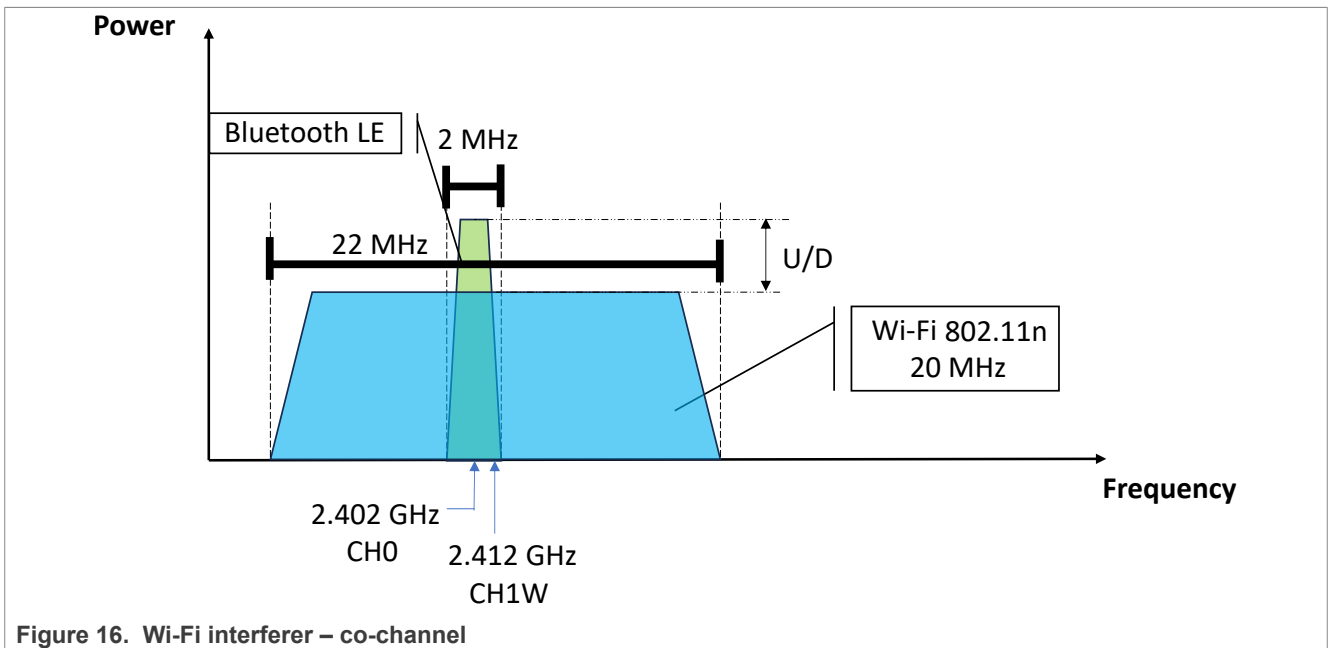
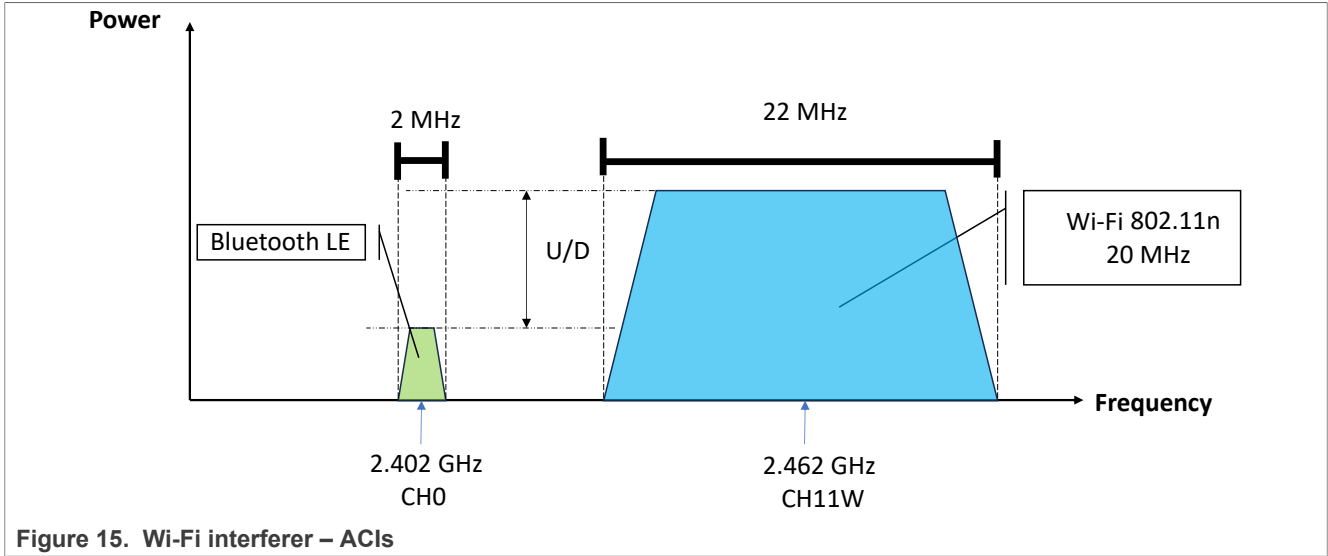
4.1.2 Signal definition

A real Wi-Fi signal has been sampled and used for this test series:

- 802.11n mode, 20 MHz bandwidth (signal antenna).
- Access point (client) is sending datagrams to station (server).
- The theoretical data rate set on the AP is 100 Mbit/s (full load).
- A report is sent back by the station every second to show the practical measured throughput (typically 58 Mbit/s).

The streaming has been sampled with a Signal analyzer (sample frequency 40 MHz, length 1 s).

IQ samples are played with an RF arbitrary generator to simulate a Controlled Wi-Fi adjacent signal.



4.2 Wi-Fi interference tests

This section describes the test methods and results to packet error rate (PER) depending on the Wi-Fi interferer.

4.2.1 ACIs test method

- Set the MCX W71 radio to: RX mode (Bluetooth LE 1 Msps, 2 Msps, 500 kbps or 125 kbps), modulated, continuous mode, frequency: channel 0 (2.402 MHz).
- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: channel 0 (2.402 MHz).
- Set the analyzer for power calibration on Bluetooth LE signal and Wi-Fi signal.

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- Wi-Fi signal (BW=22 MHz) is set from a level of -40 dBm to 0 dBm, channel 11 (2.462 GHz), and channel 6 (2.437 GHz).
- Bluetooth LE power is decreased until PER criteria (<30.8 %) is reached.

4.2.2 ACIs result

Figure 17 shows the ACIs result.

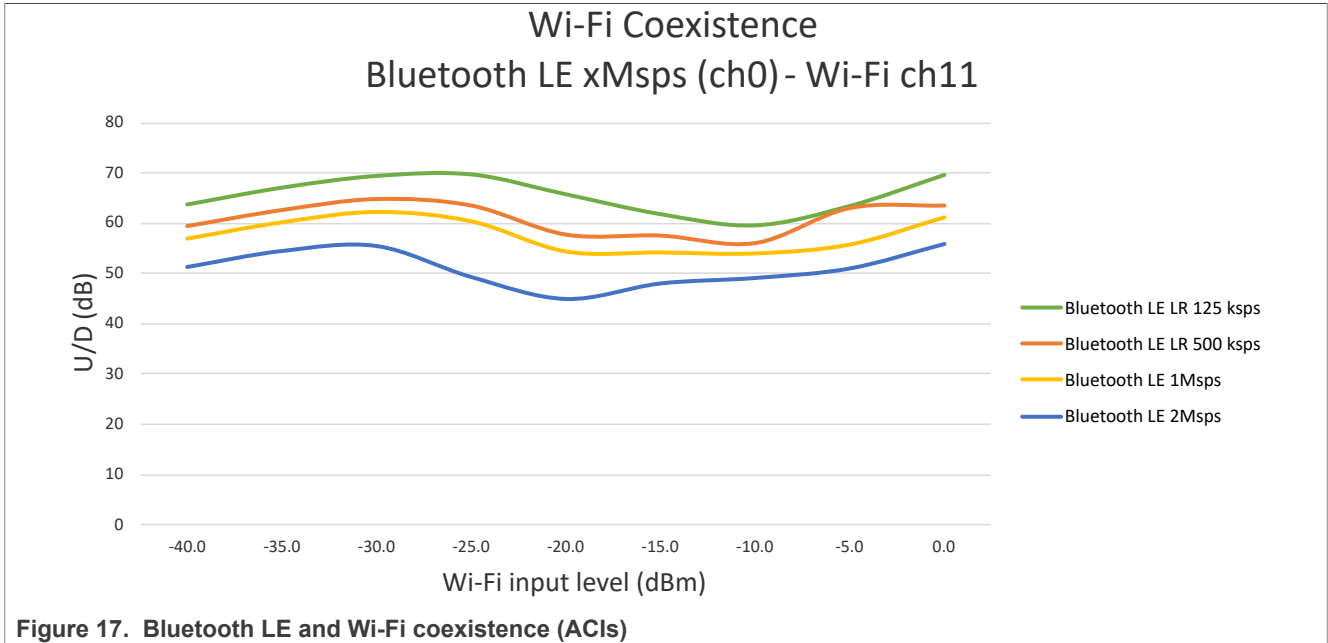


Figure 17. Bluetooth LE and Wi-Fi coexistence (ACIs)

4.2.3 Co-channel test method

- Set the MCX W71 radio to: RX mode (Bluetooth LE 1 Msps, 2 Msps, 500 kbps or 125 kbps), modulated, continuous mode, frequency: channel 0 (2.402 MHz).
- Set the generator to: Bluetooth LE modulated signal (typical 1500 packets of 37 bytes payload), continuous mode, frequency: channel 0 (2.402 MHz).
- Set the analyzer for power calibration on Bluetooth LE signal and Wi-Fi signal.
- Wi-Fi signal (BW=22 MHz) is set from a level of -40 dBm to 0 dBm, channel 1 (2.412 GHz).
- Bluetooth LE power is decreased until PER criteria (< 30.8 %) is reached.

4.2.4 Co-channel result

Figure 18 shows the Bluetooth LE and Wi-Fi co-channel test result.

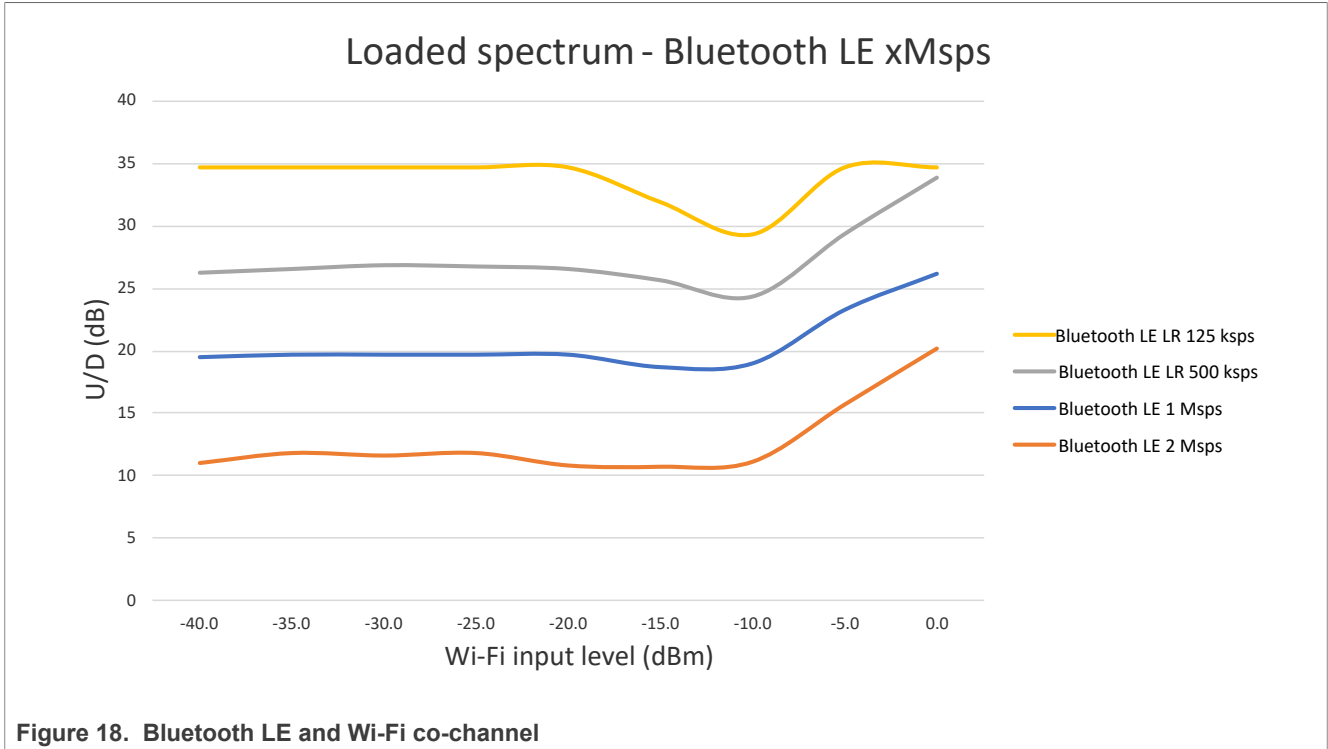


Figure 18. Bluetooth LE and Wi-Fi co-channel

4.3 Conclusion

The ratio between Unwanted and Wanted power is relatively constant whatever the Wi-Fi interferer versus Bluetooth LE rate.

5 Revision history

Table 1 summarizes the revisions to this document.

Table 1. Revision history

Document ID	Release date	Description
AN14515 v.1.0	13 January 2025	Initial public release

FRDM-MCXW71 RF System Evaluation Report for Bluetooth Low Energy Applications with Interferer Coexistence

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